

Part Number: Applicable to ASL, AFL, AHL, AXL-series.
Product Name: GaAs Amplifier
Package Type: TDFN8

Package Elements	Constituents	CAS No.	Weight (mg)	Weight %
Die	GaAs	1303-00-0	0.153	85
	Au	7440-57-5	0.027	15
Molding compound	Bisphenol a Diglycidyl Ether Resin	25068-38-6	0.117	3%
	Phenol Resin	Trade Secret	0.117	3%
	Silica(Amorphous) A	60676-86-0	3.06935	78.5%
	Silica(Amorphous) B	7631-86-9	0.5865	15%
	Carbon Black	1333-86-4	0.0196	0.5%
Die attach	Silver Powder	7440-22-4	0.1021	78.5%
	Epoxy Resin	9003-36-5	0.0143	11%
	Cresyl glycidyl ether	26447-14-3	0.0078	6%
	Phenolic Hardener	Trade Secret	0.0046	3.5%
	Dicyandiamide	461-58-5	0.0009	0.7%
	Amine Type Hardener	Trade Secret	0.0004	0.3%
Lead frame	Cu	7440-50-8	2.54	97.62%
	Fe	7439-89-6	0.0546	2.1%
	P	7723-14-0	0.00039	0.015%
	Zn	7440-66-6	0.0013	0.05%
	Pb	7439-92-1	0.00052	0.02%
	Ag	7440-22-4	0.00494	0.19%
Tin Plating	Tin	7440-31-5	0.13	100%
Gold Wire	Au	7440-57-5	0.13	100%
Total			7.08	

This information sheet is to declare all substances intentionally added in our TDFN8 semiconductor products. Total weight of the package varies depending on active die size. The material data is evidenced by written declaration from our packaging company. The products listed above DO NOT CONTAIN intentionally added hazardous materials such as cadmium (Cd), mercury (Hg), hexavalent chromium (Cr⁶⁺), polybrominated biphenyls (PBBs), polybrominated diphenylethers (PBDEs), bis(2-ethylhexyl) phthalate (DEHP), butyl benzyl phthalate (BBP), dibutyl phthalate (DBP), and diisobutyl phthalate (DIBP) except for 0.01 wt.% of lead (Pb), which **COMPLY with the RoHS3 Directive 2015/863/EU**. For further information, contact our Sales Department at sales@asb.co.kr.


 Authorized Signature, ASB Inc.

This data is based on information provided by our suppliers and we do not validate it by measurement. ASB Inc. assumes no responsibility in connection with any use of this information. The information is subject to change without notice.

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